L Number	Hits	Search Text	DB	Time stamp
5	3	(("6344401") or ("6165885") or ("5834320")).PN.	USPAT	2004/01/12 07:56
6	244	(wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<=20000616	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/12 08:03
7	244	(wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<=20000616	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/12 08:04
8	166	((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<=20000616) and align$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/12 08:05
9	688	(438/455).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/12 08:08
12	12	438/455,456,457,458,459,460,461,462,464.ccls and (wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or ("BGA")) and (dic$4 or cut$4 or separat$5)) and @ad<=20000616	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/12 08:11
11	97	438/$.ccls. and (wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or ("BGA")) and (dic$4 or cut$4 or separat$5)) and @ad<=20000616	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/12 08:52
-	348	(438/15).CCLS.	USPAT	2004/01/12 08:08
-	258	(438/113).CCLS.	USPAT	2002/07/03 08:58
-	94	(438/110).CCLS.	USPAT	2002/07/03 08:58
-	59	(438/114).CCLS.	USPAT	2002/07/03 08:58
-	681	438/15,110,113,114.ccls.	USPAT	2002/12/19 14:38
-	401	438/15,110,113,114.ccls. and test$3	USPAT	2001/08/07 15:09
-	272	(438/15,110,113,114.ccls. and test$3) and (dice$4 or cut$5)	USPAT	2001/08/07 15:10
-	901	438/15,110,113,114.ccls.	USPAT; EPO; JPO; DERWENT	2002/02/04 09:53
-	460	438/15,110,113,114.ccls. and test$3	USPAT; EPO; JPO; DERWENT	2002/02/04 09:54
-	325	(438/15,110,113,114.ccls. and test$3) and (dic$5 or cut$5)	USPAT; EPO; JPO; DERWENT	2002/02/05 08:26
-	5	(("6077757") or ("6335224") or ("6309943") or ("6309909") or ("6326697")).PN.	USPAT	2003/10/24 12:32
-	7	(("6077757") or ("6335224") or ("6309943") or ("6309909") or ("6326697") or ("5858815") or ("5137836")).PN.	USPAT	2002/02/05 09:49
-	326	(438/15,110,113,114.ccls. and test$3) and (dic$5 or cut$5)	USPAT; EPO; JPO; DERWENT	2002/02/05 08:28
-	0	((438/15,110,113,114.ccls. and test$3) and (dic$5 or cut$5)) and (magnet$7 adj align$5)	USPAT; EPO; JPO; DERWENT	2002/02/05 08:33
-	170	((438/15,110,113,114.ccls. and test$3) and (dic$5 or cut$5)) and (align$5)	USPAT; EPO; JPO; DERWENT	2002/02/05 08:32
-	2705	magnet$7 adj align$5	USPAT; EPO; JPO; DERWENT	2002/02/05 08:56
-	0	(magnet$7 adj align$5) and (wafer adj20 dielectric adj tape)	USPAT; EPO; JPO; DERWENT	2002/02/05 08:37

-	0	wafer adj20 dielectric adj tape	USPAT; EPO; JPO; DERWENT	2002/02/05 08:37
-	0	wafer adj dielectric adj tape	USPAT; EPO; JPO; DERWENT	2002/02/05 08:38
-	248	(magnet$7 adj align$5) and semiconductor	USPAT; EPO; JPO; DERWENT	2002/02/05 08:57
-	0	((magnet$7 adj align$5) and ring) and (charged adj slot)	USPAT; EPO; JPO; DERWENT	2002/02/05 08:49
-	0	(magnet$7 adj align$5) and (charged adj slot)	USPAT; EPO; JPO; DERWENT	2002/02/05 08:49
-	613	(magnet$7 adj align$5) and ring	USPAT; EPO; JPO; DERWENT	2002/02/05 08:50
-	47	((magnet$7 adj align$5) and ring) and semiconductor	USPAT; EPO; JPO; DERWENT	2002/02/05 08:51
-	3066	optically adj align$5	USPAT; EPO; JPO; DERWENT	2002/02/05 08:56
-	612	(optically adj align$5) and semiconductor	USPAT; EPO; JPO; DERWENT	2002/02/05 08:57
-	8	(("6077757") or ("6335224") or ("6309943") or ("6309909") or ("6326697") or ("5858815") or ("5137836") or ("4781969")).PN.	USPAT	2003/06/02 08:10
-	10260	wood.inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/03 08:13
-	539	wood.inv. and alan	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/03 08:13
-	232	(wood.inv. and alan) and (micron adj technology)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/03 08:14
-	1	("6268650").PN.	USPAT	2002/12/20 10:24
-	425	(438/15).CCLS.	USPAT	2002/07/08 08:43
-	331	(438/113).CCLS.	USPAT	2002/07/08 08:57
-	140	(438/110).CCLS.	USPAT	2002/07/08 08:57
-	90	(438/114).CCLS.	USPAT	2002/07/08 08:57
-	425	(438/15).CCLS.	USPAT	2002/07/08 08:43
-	331	(438/113).CCLS.	USPAT	2002/07/08 08:57
-	140	(438/110).CCLS.	USPAT	2002/07/08 08:57
-	90	(438/114).CCLS.	USPAT	2002/07/08 14:32
-	13	(("6389689") or ("5977629") or ("5796170") or ("6326700") or ("6268650") or ("5858815") or ("5817535") or ("5770032") or ("4781969") or ("5073840") or ("5696033") or ("5834839") or ("6160714")).PN.	USPAT	2002/07/08 10:35
-	8	(("6309909") or ("5858815") or ("5137836") or ("6077757") or ("6326697") or ("6165885") or ("5834320") or ("4781969")).PN.	USPAT	2002/07/09 09:56
-	0	(wafer adj (bond$3 or attach$3) near4 (dielectric adj (layer or film))) same test$3 same (cut$4 or dic$3 or separat$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:00

-	0	(wafer adj (bond$3 or attach$3) near4 (dielectric adj (layer or film))) same test$3 same (cut$4 or dic$3 or separat$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 14:07
-	19	wafer adj (bond$3 or attach$3) near4 (dielectric adj (layer or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 14:07
-	0	(wafer adj (bond$3 or attach$3) near4 (dielectric adj (layer or film))) same test$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 14:38
-	963	438/15,110,113,114.ccls.	USPAT	2002/12/19 14:38
-	1212	438/15,110,113,114.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 14:38
-	0	438/15,110,113,114.ccls. and ((wafer adj (bond$3 or attach$3) near4 (dielectric adj (layer or film))) same test$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 14:40
-	9	(wafer adj (dielectric adj (layer or film))) same test$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/20 08:18
-	13	(("5834839") or ("6389689") or ("6160714") or ("5977629") or ("6326700") or ("6268650") or ("5858815") or ("5817535") or ("5770032") or ("5796170") or ("4781969") or ("5073840") or ("5696033")).PN.	USPAT	2002/12/19 15:19
-	85	wafer same dielectric same test$3 same (cut$3 or dic$3 or slic$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/20 08:42
-	78	(wafer same dielectric same test$3 same (cut$3 or dic$3 or slic$3)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/20 09:38
-	348	(wafer same (dielectric adj (layer or film))) same test$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/20 09:35
-	322	((wafer same (dielectric adj (layer or film))) same test$3) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/20 09:38
-	98	(((wafer same (dielectric adj (layer or film))) same test$3) and semiconductor) and (cut$3 or dic$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/20 09:39
-	1	("6424023").PN.	USPAT	2002/12/20 10:24
-	3	(("5897337") or ("5858815") or ("6389689")).PN.	USPAT	2002/12/23 11:53
-	2	(("5897337") or ("6389689")).PN.	USPAT	2002/12/23 11:53
-	9187	((balls adj grid adj arrays) or (BGA)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/20 07:59

-	4418	(((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic$4 or cut$4 or separat$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/20 08:02
-	4476	(((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic$4 or cut$4 or separat$5 or saw$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/20 08:04
-	955	((((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic$4 or cut$4 or separat$5)) and (metal adj (film or layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/20 08:04
-	970	((((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic$4 or cut$4 or separat$5 or saw$4)) and (metal adj (film or layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/20 08:04
-	1	("20010052642").PN.	US-PGPUB	2003/05/20 08:12
-	472	wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/20 08:52
-	233	(wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<=20000616	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/12 08:09
-	212	((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<=20000616) and (dic$5 or cut$6 or saw$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/21 08:23
-	206	((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<=20000616) and (dic$5 or cut$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/20 09:06
-	1	(((wafer adj semiconductor) same (metal adj (film or layer)) same (attach$5 or bond$4) same ((balls adj grid adj arrays) or (BGA)) same (dic$4 or cut$4 or separat$5)) same (dic$5 or cut$6 or saw$5)) and @ad<=20000616	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/20 10:06
-	212	((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<=20000616) and (dic$5 or cut$6 or saw$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/21 09:00
-	172	(((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<=20000616) and (dic$5 or cut$6 or saw$5)) and dic$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/21 09:24
-	92	(((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<=20000616) and (dic$5 or cut$6 or saw$5)) and (dicing or diced)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/21 09:35

-	70	((((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<=20000616) and (dic$5 or cut$6 or saw$5)) and (dicing or diced)) and (individual$3 or each)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/21 09:36
-	70	((((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<=20000616) and (dic$5 or cut$6 or saw$5)) and (dicing or diced)) and (individual$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/21 09:36
-	6	((((wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<=20000616) and (dic$5 or cut$6 or saw$5)) and (dicing or diced)) and (individual$3 adj device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/21 09:37
-	2	(("6344401") or ("6566745")).PN.	USPAT	2004/01/12 07:56
-	241	(wafer and (metal adj (film or layer)) and (attach$5 or bond$4) and ((balls adj grid adj arrays) or ("BGA")) and semiconductor and (dic$4 or cut$4 or separat$5)) and @ad<=20000616	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/12 08:10
-	1	((wafer same (metal adj (film or layer)) same (attach$5 or bond$4) same ((balls adj grid adj arrays) or ("BGA")) same semiconductor same (dic$4 or cut$4 or separat$5))) and @ad<=20000616	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/23 10:36
-	2	(("6153448") or ("20020011859")).PN.	USPAT; US-PGPUB	2003/10/24 12:35
-	4	(("6153448") or ("20020011859") or ("6064217") or ("5475317")).PN.	USPAT; US-PGPUB	2003/10/24 14:07